♥ MERCURY[™]+ Batch Spray Clean Etch System

Industry Proven High Volume Batch Spray Technology

CLEAN ETCH STRIP

Features

- Available for 100mm to 200mm wafer sizes
- Low Cost/Compact Footprint
- Up to 6 different chemical inputs
- High chemical temperature capability
- Freshly mixed chemistry

High Throughput, Low CoO



SHELLBACK







Ideal For SiC & Power Devices

Applications

- SPM, dHF, SC1, SC2 cleans
- Post-etch and Post-ash cleans
- Aqueous photoresist strip
- Wet etch/strip of metal films for silicide
- BEOL Post cleans using DSP, DSP+

Benefits

- High throughput batch cleaning, 100 to 200 wafers per batch
- Reliable, low cost of ownership
- Proven Platform for 100mm to 200mm
- Flexible chemistries



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Industry Proven High Volume Batch Spray Technology

Centrifugal Batch Spray Technology



High centrifugal force generates strong fluid dynamics for enhanced cleaning and stripping efficiency

New Advanced Control System



New interactive maintenance screen



Classic Mode screen for experienced operators

Control System Specifications			
Display	15" HD Touchscreen		
CPU / Speed	2.3 GHz, Dual Core		
Analog / Digital I/O	Ethercat, Extendable		
Pneumatic Outputs	Ethercat, Extendable		
USB	4 Ports		
Hard Drive	320 GB		
Ethernet	4 Ports		
Operating System	Windows 10		
Software Extendable	Yes		
Custom Monitoring	Yes		
Data Logging	Yes		
Graphical User Interface	Yes		





product information



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Dynamic Rinse & Ramping

Accelerated Contaminant Removal



Mercury[™]+ Specifications

Wafer Size	100mm	150mm	200mm
Wafers per Batch	200	150	100
Throughput Post Ash Clean Recipe	378 WPH	302 WPH	201 WPH
Footprint	2.7 m ²		
On Wafer Temp Capability	120°C		
Chemical Dispense Method	Single Pass (6 chemicals)		

Dimensions





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